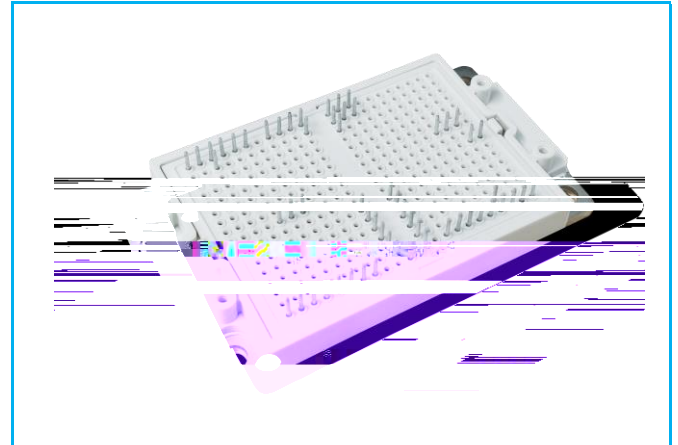


## PRODUCT FEATURES

- 1200V IGBT CHIP
- Low VCE(sat) and Low switching losses
- Free wheeling diodes with fast and soft reverse recovery



## APPLICATIONS

- 3-Level-Applications
- Solar Applications
- PCS

## MODULE CHARACTERISTICS ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$T_{Jop}$	Operating Temperature		-40~150	°C
$T_{stg}$	Storage Temperature		-40~125	
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3200	V
RTI	RTI Elec.	housing	140	°C
CTI	Comparative Tracking Index		>400	
Md	Mounting Torque	Recommended (M5)	2.5~5	Nm

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Unit

°C

W

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Unit

nA

μC

nF

nF

nF

ns

ns

ns

ns

ns

ns

mJ

mJ

mJ

ns

1290

ns

$T_J=150^\circ\text{C}$

ns

60

ns

ns

115

ns

9.7

mJ

mJ

14.9

mJ

K/W

# MMG450WQ120PD6T7

				Unit
$I_{CDC}$	Continuous DC Collector Current	$T_C=100^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$		°C W
$Q_G$				nA
$C_{ies}$	Input Capacitance		63.6	nF
$C_{res}$	Reverse Transfer Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=100\text{kHz}$		nF
$t_{d(on)}$	Turn on Delay Time	$T_J=25^\circ\text{C}$ $T_J=125^\circ\text{C}$ $T_J=150^\circ\text{C}$	129 113	ns ns ns ns ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=650\text{V}, I_C=200\text{A}$ $R_{Goff}$ $V_{GE}=\pm 15\text{V},$ Inductive Load ( $T_J=150^\circ\text{C}$ )	44 92 115 10.3	ns ns ns mJ mJ mJ
$E_{off}$	Turn off Energy	$T_J=125^\circ\text{C}$	15.7	mJ
$R_{thJC}$	Junction to Case Thermal Resistance		0.107	K/W

## MMG450WQ120PD6T7

Diode(D2、D3)

ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
$I_{FN}$	Implemented Forward Current		280	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	560	
$I^2t$		$T_{vj}=25^\circ\text{C}$ , $t=10\text{ms}$ , 50Hz	9100	$\text{A}^2\text{s}$
$T_{Jmax}$	Max. Junction Temperature		175	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=280\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=25^\circ\text{C}$		2.80		V
		$I_F=280\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=125^\circ\text{C}$		2.30		
		$I_F=280\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=150^\circ\text{C}$		2.15		
$R_{thJC}$	Junction to Case Thermal Resistance				0.250	K/W

Diode(D1、D4、D5、D6)

ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
$I_{FN}$	Implemented Forward Current		250	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	500	
$I^2t$		$T_{vj}=25^\circ\text{C}$ , $t=10\text{ms}$ , 50Hz	16200	$\text{A}^2\text{s}$
$T_{Jmax}$	Max. Junction Temperature		175	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=250\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=25^\circ\text{C}$		1.34	1.65	V
		$I_F=250\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=125^\circ\text{C}$		1.6		
		$I_F=250\text{A}$ , $V_{GE}=0\text{V}$ , $T_J=150^\circ\text{C}$		1.66		
$R_{thJC}$	Junction to Case Thermal Resistance				0.163	K/W

NTC CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$R_{25}$	Resistance	$T_{NTC}=25^\circ\text{C}$		5		
$\Delta R/R$	$T_{NTC}=100^\circ\text{C}$ , $R_{100}$		-5		5	%
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15\text{K}))]$			3375		K

# MMG450WQ120PD6T7

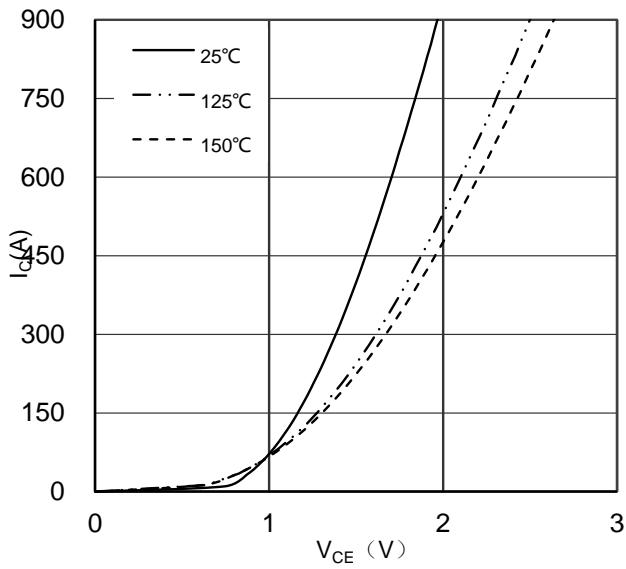


Figure 1. Typical Output Characteristics IGBT

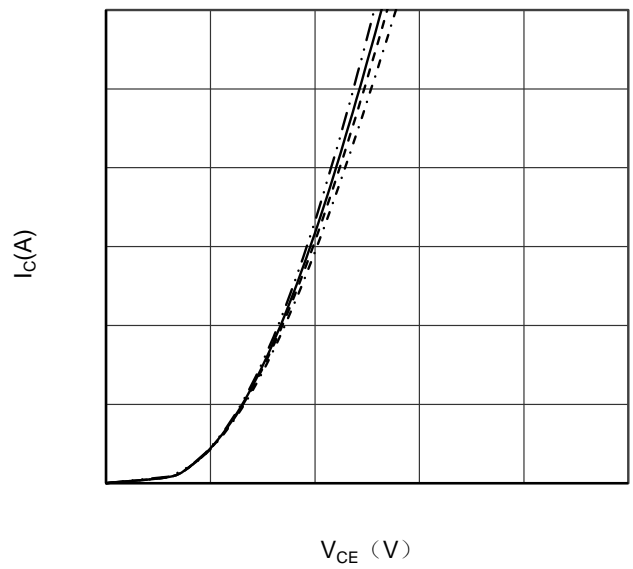


Figure 2. Typical Output Characteristics IGBT



Figure 3. Typical Transfer characteristics IGBT

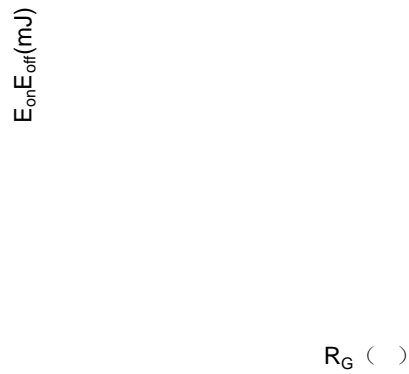


Figure 4. Switching Energy vs Gate Resistor IGBT (T1, T4)

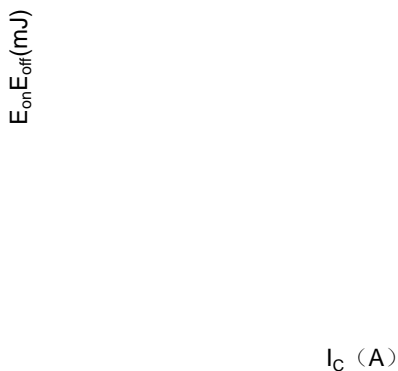


Figure 5. Switching Energy vs Collector Current IGBT (T1, T4)

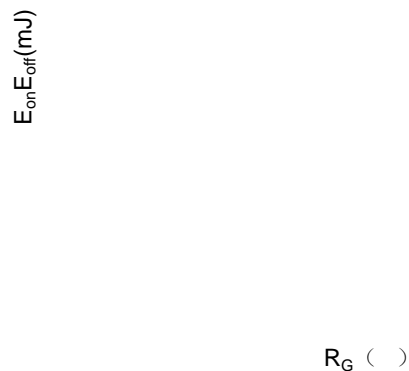


Figure 6. Switching Energy vs Gate Resistor IGBT (T2, T3)

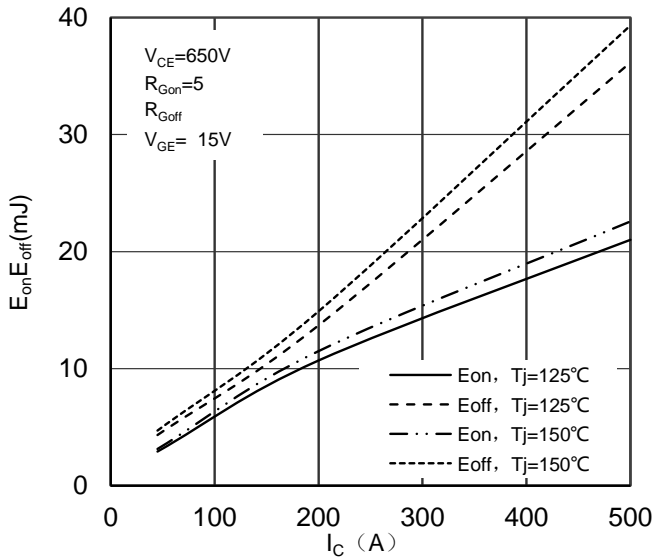


Figure 7. Switching Energy vs Collector Current IGBT (T2, T3)

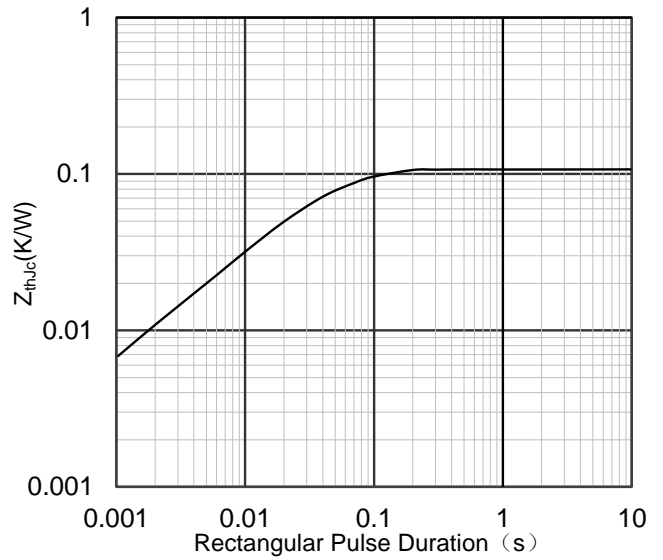


Figure 8. Transient Thermal Impedance of IGBT

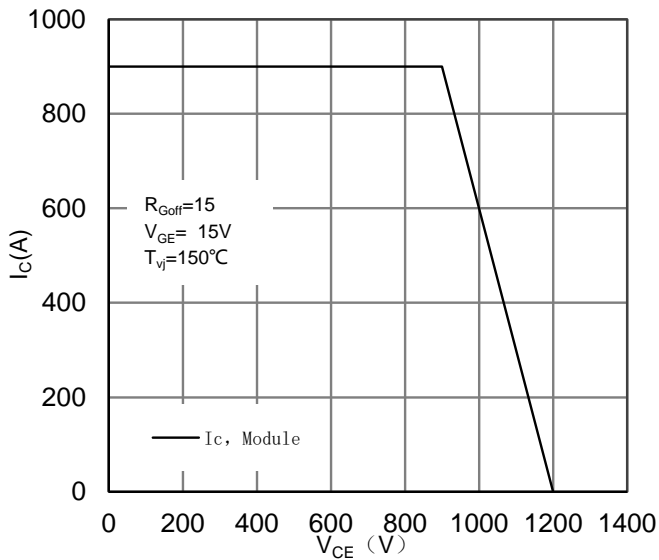


Figure 9. Reverse Bias Safe Operating Area IGBT

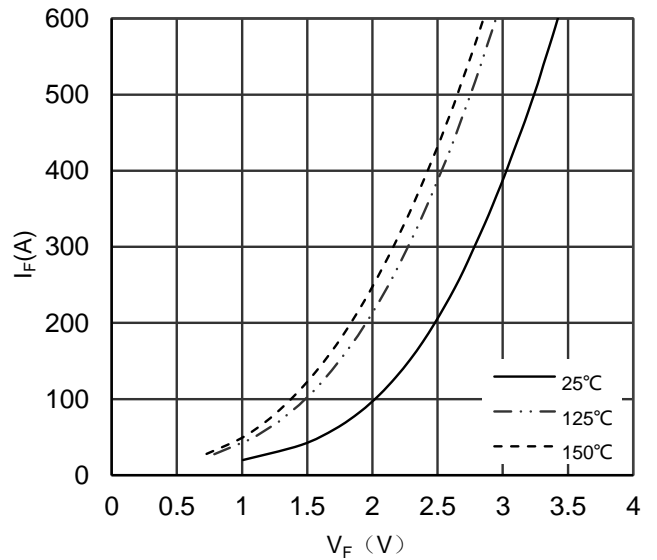


Figure 10. Diode Forward Characteristics Diode (D2, D3)

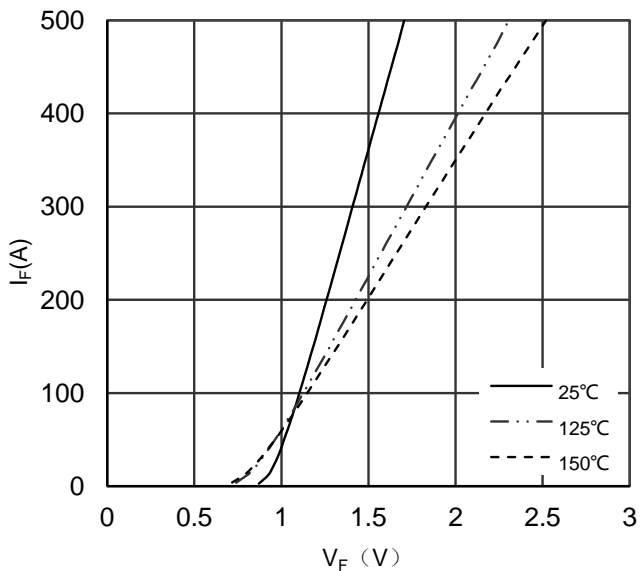


Figure 11. Diode Forward Characteristics Diode (D1, D4, D5, D6)

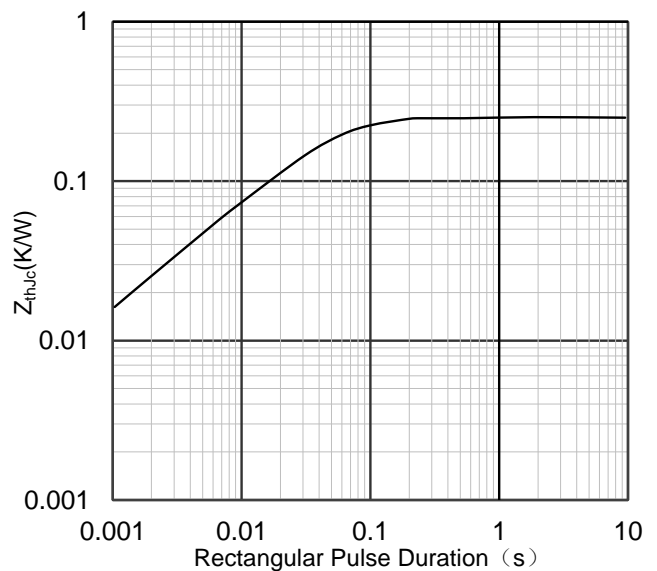


Figure 12. Transient Thermal Impedance of Diode (D2, D3)

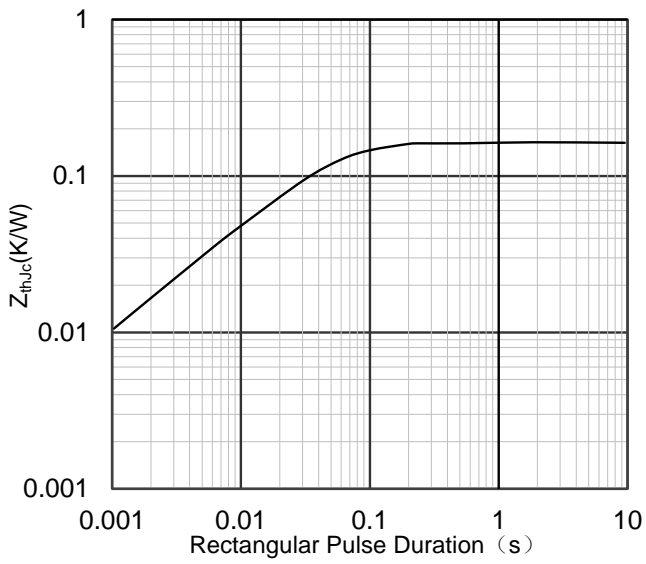


Figure 13. Transient Thermal Impedance of Diode (D1, D4, D5, D6)

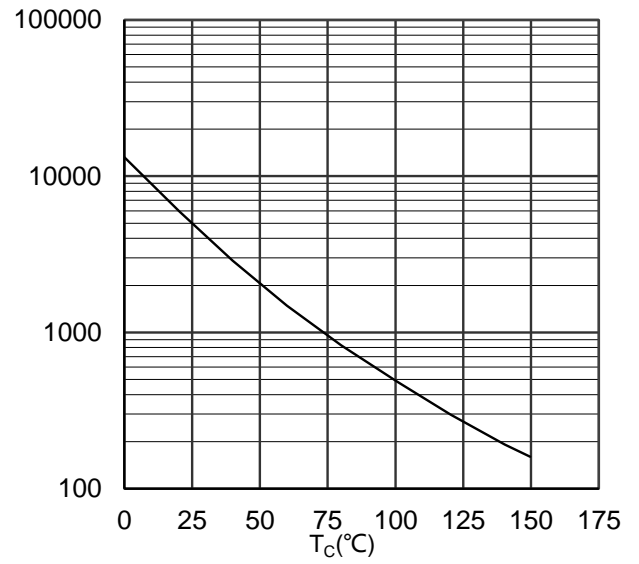


Figure 14. NTC Characteristics

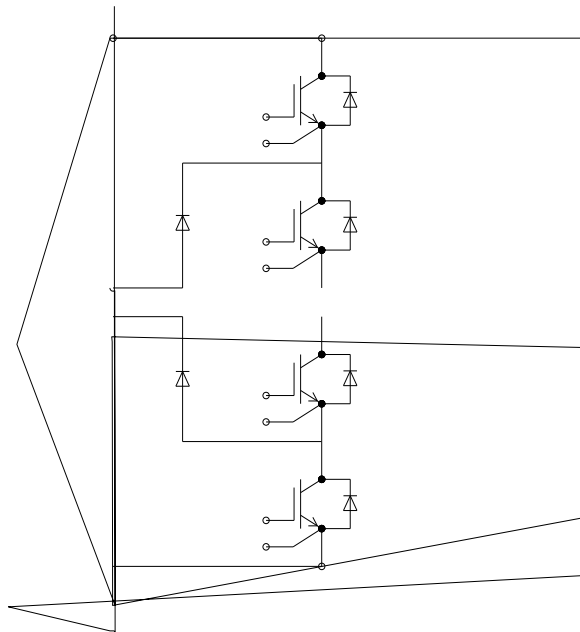


Figure 15. Circuit Diagram

